ICEPT 2026

27th International Conference on Electronic Packaging Technology

第27届电子封装技术国际会议

August 5-7th , Xi'an·China

西安交通大學
XI'AN JIAOTONG UNIVERSITY

The 27th International Conference on Electronic Packaging Technology

Call for papers

2026 27th International Conference on Electronic Packaging Technology (ICEPT) will be held in Xi'an, China, from August 5th to 7th, 2026. The conference is hosted by Institute of microelectronics, Chinese Academy of Sciences, Xi'an Jiaotong University, IEEE-EPS and CIE-EMPT. It is organized by the School of Microelectronics of Xi'an Jiaotong University, National Center for Advanced Packaging Co., Ltd., Shaanxi Semiconductor Industry Association and Beijing Herogees Consulting Company.

It has become one of the four major brand conferences in the field of international electronic packaging. At present, Moore's Law has reached an inflection point, semiconductor manufacturing technology is facing challenges, and new packaging technologies are constantly emerging. The conference will provide an academic communication platform for experts, scholars and researchers worldwide on new progress and new ideas of electronic packaging and manufacturing technology.

During the three-day event, participants from many countries and regions will share the latest technological developments of electronic packaging technologies via special lectures, invited talks, theme forums, technical sessions, exhibitions, poster presentations and other forms. We sincerely invite you to join in this event!

CONFERENCE TOPICS

- **Advanced Packaging:** 2.5D and 3D packaging, chiplet, wafer-level/panel-level fan -out and fan-in packaging, flip chip packaging, advanced packaging thermal management, system integration, other heterogeneous integration packaging technologies.
- **Packaging Materials & Processes:** Packaging materials, green/nano packaging materials, high-end packaging substrate, self-alignment and assembly technologies, other packaging-related semiconductor materials and processes.
- **Packaging Design & Modeling:** Design, modeling, methodology and simulation technologies of complex packaging, cross-scale and multi-physics modeling, process simulation technologies, etc.
- **Interconnection Technologies:** TSV, TGV, bumping and micro copper pillar technologies, high density inter-connection technologies, hybrid bonding technologies, nano-materials bonding technologies, chip-to-wafer/panel and wafer-to-wafer interconnect technologies, thermocompression bonding technologies, other new inter-connection technologies.
- **Advanced Manufacturing:** Manufacturing, Assembly, testing and other automated packaging and testing equipment under the traction of advanced packaging technology, new principle packaging and testing equipment, main or key components and module technology of equipment.
- **Quality & Reliability:** Test technologies for packaging, new reliability experiment technologies, reliability evaluation method, methodologies for reliability data collection and analysis, reliability modeling, life prediction, failure analysis and non-destructive diagnose.
- **Power Electronics & Energy Electronics:** Power electronic packaging related interconnection, thermal management and substrate technology, wide bandgap semiconductor packaging technology, ultra-wide bandgap semiconductor packaging technology, IGBT, SiC, GaN hybrid packaging technology, high voltage packaging technology, high junction temperature packaging technology, multi-functional integrated packaging technology, other power semiconductor packaging technology, switching, isolated/non-isolated power supply, inverter, IPM, POL, PSiP and other power module packaging and integration methods, power module control algorithm, EMI modeling and optimization, Industrial modules and vehicle-scale groups and systems, other new energy and new power

electronic modules.

- **Optoelectronics and New Display:** Design, simulation, interconnection, packaging, reliability, and failure analysis technologies for optoelectronic and heterogenous integration within packages, including optical displays, optical communications, optical sensing, lasers, and emerging display technologies.
- **RF Electronic Packaging:** Interactive Design of RF Integrated Circuits and Packaging, Design of RF Packaging and Modules, RF Heterogeneous Integration Processes, Integration of RF Passive Devices, Thermal Management of RF Devices and Systems, Reliability of RF Packaging, Millimeter Wave/THz packaging, Integration of Antenna and Packaging, Suppression of RF Noise in Packaging, SAW/BAW Resonators, Filter-related Technologies, etc.
- **Emerging Technologies:** Packaging technologies suitable for increasing the bandwidth and scale of large computing power chips, integrated power supply technology for large computing power chips, efficient heat dissipation technology for large computing power chips, brain-computer interfaces, vertical power delivery, packaging and integration of emerging devices, packaging of novel two-dimensional (2D) material-based devices, quantum technologies, MEMS/NEMS packaging, sensor packaging, implantable device packaging, microfluidic 3D printing Packaging, wafer-level and panel-level packaging for MEMS and sensors, wearable/flexible and bioelectronic packaging, etc.
- **AI-Enabled Packaging Technologies：** AI/ML-driven design, surrogate modeling, and co-optimization, ML/DL for quality control, process optimization, reliability prediction, and failure analysis, generative AI, digital twin, AI-assisted co-design of chip, package, and system integration. Advanced packaging architectures and technologies (Heterogeneous Integration, 2.5D/3D, Chiplet) for high-performance AI, power delivery, signal integrity, and thermal management for AI systems, system-level solutions, etc.

IMPORTANT DATES

~~March 20th, 2026 | Deadline for Submission of Abstract~~

~~April 20th, 2026 | Notification of Abstract Acceptance~~

May 27th, 2026 | Deadline for Submission of Full Paper

June 30th, 2026 | Notification of Full Paper Acceptance

SUBMISSION OF ABSTRACT

Abstracts are solicited to describe original and unpublished work. The abstract should be approx. 500 words and contains a clear statement of the background, methodology, results, and conclusions. All abstracts and manuscripts must be in English and should be submitted through online submission system. The instructions for abstract submission can be found at the conference website http://www.icept.org. All accepted manuscripts will be submitted for inclusion into IEEE Xplore. Selected papers will be recommended for publication in related IEEE/EPS journals.

Abstract Submission Website:
https://easychair.org/conferences?conf=icept2026

BEST PAPER AWARD

Best papers and posters will be selected and awarded at the conference.

CALL FOR EXHIBITION/SPONSORSHIP

A tabletop exhibition featuring suppliers of materials, equipment, components, software, manufacturers, and service providers of the electronics packaging and related industries will be held during the conference. Potential exhibitors and sponsors may e-mail to janey@fsemi.tech for details.

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